

# NDiS M537

Embedded Computer Powered by 7th/6th Gen. Intel® Core™ Processor  
OPS PLUS-Based Digital Signage Platform, Support 4K Resolution



## Main Features

- ♦ 7th/6th generation Intel® Core™ processor
- ♦ Intel® integrated HD 630 graphic engine
- ♦ Support 3 independent 4K2K video out
- ♦ Dual DDR4 SO-DIMM support
- ♦ Support Wi-Fi module
- ♦ DirectX® 12 support

## Product Overview

NDiS M537 is an OPS PLUS-compliant media player powered by 7th/6th generation Intel® Core™ processors. Following open pluggable standard, NDiS M537 can perfectly fit into a myriad of OPS PLUS-panels and is compact in size. Yet, NDiS M537 has high scalability, allowing for easy storage capacity expansion through pluggable M.2 storage unit and effortless functional extension through FX18-60P (PCIe x4, DP1.2) expansion modules. Changing system memory is also made simple. In addition, NDiS M537 leverages the future generation Intel® Core™ processors to deliver outstanding graphics support 3 independent 4K2K video output. The superb but power-efficient NDiS M537 can therefore maximize visual impacts for digital signage applications.

## Specifications

### CPU Support

- ♦ 7th generation Intel® Core™ processor (LGA1151), 35W
- ♦ 6th generation Intel® Core™ processor (LGA1151), 35W

### Chipset

- ♦ Intel® Q170 PCH

### Graphic

- ♦ Intel® integrated HD 630 graphics

### Main Memory

- ♦ 2 x 260-pin SO-DIMM sockets, supports DDR4 2133/2400 MHz non-ECC, un-buffered memory up to 32G (single socket max. 16GB)

### I/O Interface-Front

- ♦ 1 x Power button with LED
- ♦ 1 x Reset button
- ♦ 1 x RJ45 with LEDs for Gigabit LAN
- ♦ 1 x Mini DP connector for DisplayPort++
- ♦ 2 x USB 3.0
- ♦ 1 x Storage active LED
- ♦ 2 x Antenna hole
- ♦ 1 x Mic-in phone jack
- ♦ 1 x Line-out phone jack
- ♦ 1 x DB9 for RS232 (COM3)

### I/O Interface-Rear (TX25)

- ♦ 1 x TMDS (HDMI 2.0)
- ♦ 1 x USB 3.0

- ♦ 2 x USB 2.0
- ♦ 1 x UART (3.3V TTL) (COM2)
- ♦ 1 x Audio out L/R
- ♦ DC input +12V~+19V
- ♦ Control signals (PWR\_STATUS, PS\_ON#, PB\_DET, CEC, SYS\_FAN)

### I/O Interface-Rear (FX18)

- ♦ 1 x GPIO signal
- ♦ 2 x I2C signal
- ♦ LAN managements signals
- ♦ 1 x DP1.2 signal
- ♦ PCIe x4 signal

### Storage Device

- ♦ 1 x M.2 2242, SATA signal

### Expansion

- ♦ 1 x M.2 2230 for optional Wi-Fi module

### Dimensions

- ♦ 200mm (W) x 119mm (D) x 30mm (H) (7.8" x 4.7" x 1.1")

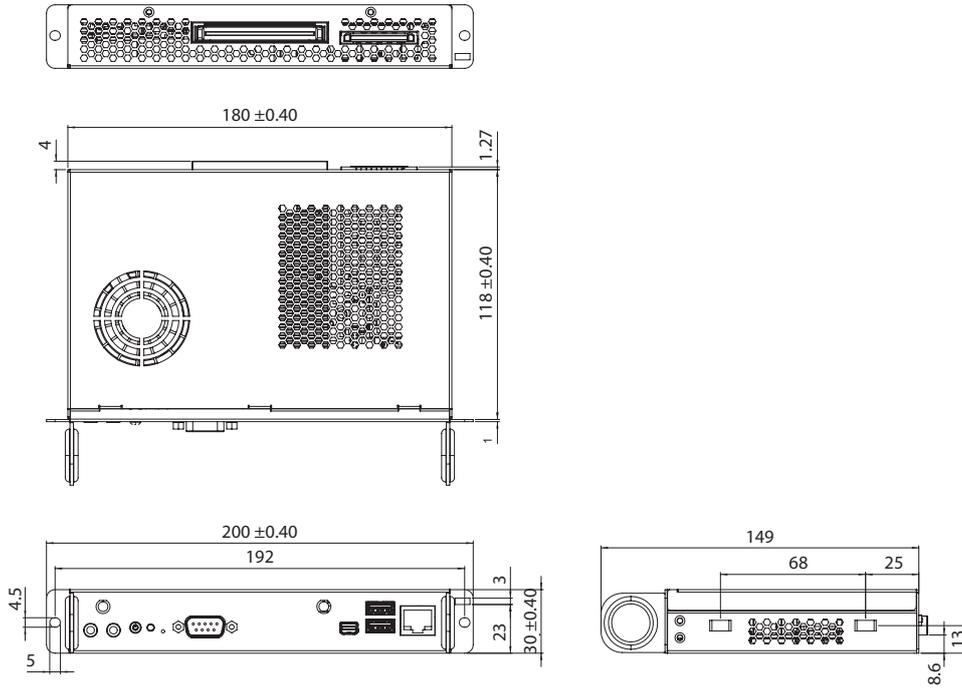
### Power Power Supply

- ♦ DC power input +12V~+19V

### Environment

- ♦ Operating temperature: ambient with air flow from 0°C to 45°C
- ♦ Storage temperature: -20°C to 80°C
- ♦ Humidity: 95% (non-condensing)

## Dimension Drawing



### Certification

- CE/FCC Class A

### Operating System

- 7th generation Intel® Core™: Win10 (64-bit)
- 6th generation Intel® Core™: Win7 (32/64-bit)/Win10 (64-bit)

### Ordering Information

- ♦ **NDiS M537 (P/N: 10W00M53700X0)**  
7th/6th generation Intel® Core™ LGA1151 type processor OPS PLUS,  
Intel® Q170 chipset